

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

TSSOP Exp. Pad

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**TOTAL MASS (g) : 0.079212**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.005343	1000000	67452.328125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.026547	975000	335140.71875		
		Iron (Fe)	7439-89-6	0.000653	24000	8243.75292969		
		Phosphorus (P)	7723-14-0	0.000008	300	100.995429993		
		Zinc (Zn)	7440-66-6	0.000019	700	239.864135742		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.027227</b>	<b>1000000</b>	<b>343725.3125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002940	1000000	37109.5546875		
		<b>External Plating Total:</b>				<b>0.002940</b>	<b>1000000</b>	<b>37109.5546875</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001123	1000000	14177.234375		
<b>Internal Plating Total:</b>				<b>0.001123</b>	<b>1000000</b>	<b>14177.234375</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001355	750000	17106.1015625		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000452	250000	5706.24169922		
<b>Die Attach Total:</b>				<b>0.001807</b>	<b>1000000</b>	<b>22812.34375</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006015	150000	75935.9375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.032882	820000	415116.5		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.001002	25000	12649.6767578		
		Carbon Black (C)	1333-86-4	0.000201	5000	2537.51025391		
		<b>Encapsulation Total:</b>				<b>0.040100</b>	<b>1000000</b>	<b>506239.59375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000672	1000000	8483.61621094		
					<b>TOTAL MASS (g) :</b>	<b>0.079212</b>		